

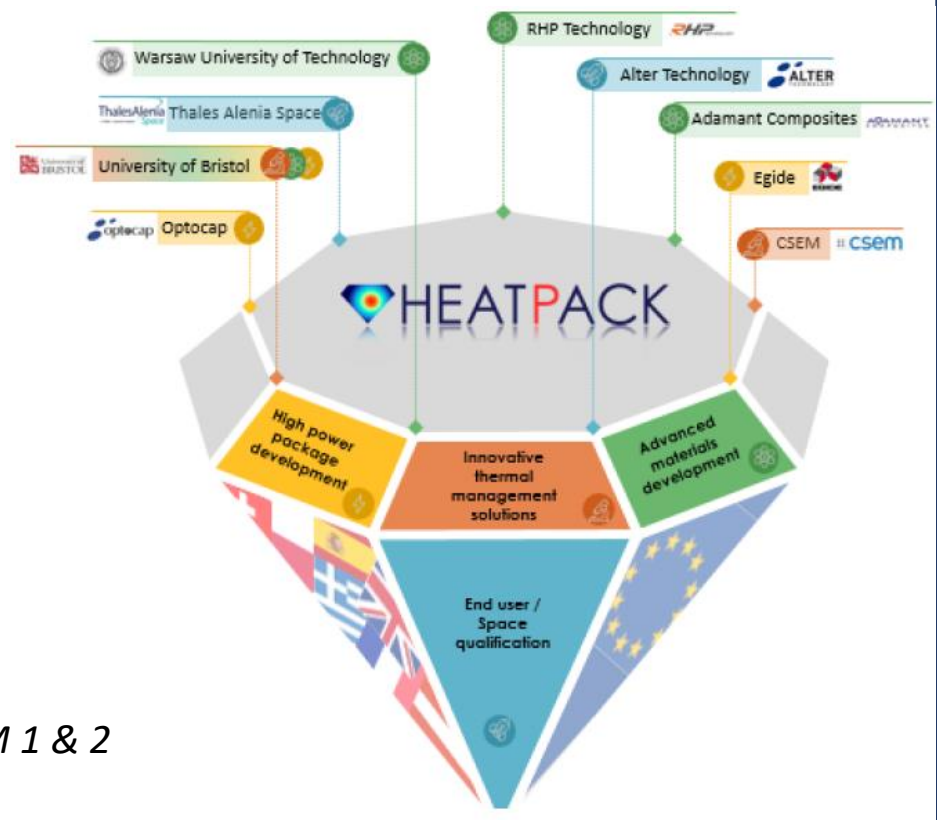
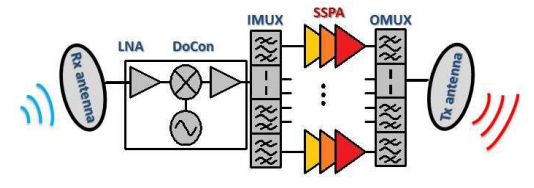
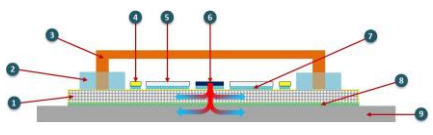
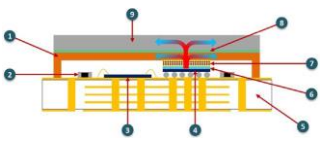
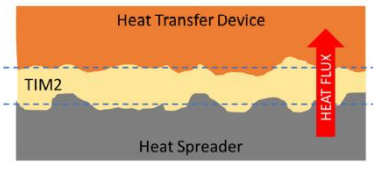
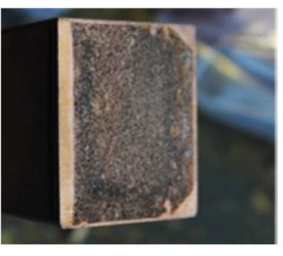
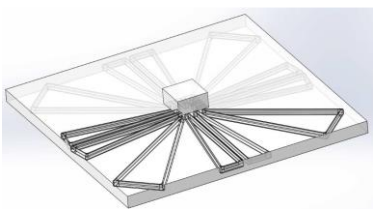
# New generation of High thERmAl efficiency componentS PACKages for space



The project aims to develop and validate **critical technology building blocks** for enabling transformative **packages** for space applications with very **low thermal resistance**. Benefits will range from improved performance to **increased components reliability & lifetime**.

## OBJECTIVE 1 Develop critical packaging building blocks for performance and reliability of high power space components

- A. *Very high thermal conductivity diamond based composite material*
- B. *1st level Thermal Interface Material based on nano-silver (TIM1)*
- C. *2nd level Thermal Interface Material (TIM2)*
- D. *Embedded micro heat pipes for in-situ cooling*
- E. *High power hermetic RF micropackage*
- F. *High power LF package*



## OBJECTIVE 2 Demonstration of the technologies

- ✓ *Demonstrators development*
- ✓ *Packages and building blocks space qualification (TIM 1 & 2 and diamond composite material)*

## PARTNERS



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